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APPLICATION NO.		FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.		
10/711,512		09/23/2004	Chien-Hung Lu	13622-US-PA	13622-US-PA 5511		
31561	7590	03/07/2006		EXAM	EXAMINER		
JIANQ CH 7 FLOOR-1		ITELLECTUAL PR	HARRISON, MONICA D				
		D, SECTION 2		ART UNIT	PAPER NUMBER		
,	100			2813			
TAIWAN				DATE MAILED: 03/07/2000	5		

Please find below and/or attached an Office communication concerning this application or proceeding.

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	Application No.	Applicant(s)	
	10/711,512	LU ET AL.	
Office Action Summary	Examiner	Art Unit	
	Monica D. Harrison	2813	
The MAILING DATE of this communication ap Period for Reply	ppears on the cover sheet w	ith the correspondence addres	;s
A SHORTENED STATUTORY PERIOD FOR REP WHICHEVER IS LONGER, FROM THE MAILING II.  - Extensions of time may be available under the provisions of 37 CFR 1 after SIX (6) MONTHS from the mailing date of this communication.  - If NO period for reply is specified above, the maximum statutory period.  - Failure to reply within the set or extended period for reply will, by statuding Any reply received by the Office later than three months after the mail earned patent term adjustment. See 37 CFR 1.704(b).	DATE OF THIS COMMUNI .136(a). In no event, however, may a red d will apply and will expire SIX (6) MON ate, cause the application to become AB	CATION. reply be timely filed ITHS from the mailing date of this commu	
Status			
1) Responsive to communication(s) filed on 14	September 2005.		
,	is action is non-final.		
3) Since this application is in condition for allow			rits is
closed in accordance with the practice under	Ex parte Quayle, 1935 C.D	). 11, 453 O.G. 213.	
Disposition of Claims			
<ul> <li>4)  Claim(s) 1-15 is/are pending in the application 4a) Of the above claim(s) is/are withdrest</li> <li>5)  Claim(s) 1-10 is/are allowed.</li> <li>6)  Claim(s) 11 is/are rejected.</li> <li>7)  Claim(s) 12-15 is/are objected to.</li> <li>8)  Claim(s) are subject to restriction and an are subject to restriction.</li> </ul>	awn from consideration.		
Application Papers			
9) The specification is objected to by the Examir	ner.		
10)☐ The drawing(s) filed on is/are: a)☐ ac	ccepted or b) objected to	by the Examiner.	
Applicant may not request that any objection to th	- · · •		
Replacement drawing sheet(s) including the corre			
11)☐ The oath or declaration is objected to by the B	=xaminer. Note the attache	d Office Action of form PTO-1	152.
Priority under 35 U.S.C. § 119			
12) Acknowledgment is made of a claim for foreign a) All b) Some * c) None of:  1. Certified copies of the priority document copies of the priority document copies of the priority document copies of the certified copies of the priority document copies of the certified copies of the priority document copies of the certified copies of the priority copies of the prior	nts have been received. nts have been received in A iority documents have been au (PCT Rule 17.2(a)).	Application No received in this National Sta	ge
Attachment(s)  1) Notice of References Cited (PTO-892)  2) Notice of Draftsperson's Patent Drawing Review (PTO-948)  3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/0: Paper No(s)/Mail Date	Paper No(	Summary (PTO-413) s)/Mail Date nformal Patent Application (PTO-15; 	2)

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### **DETAILED ACTION**

1. Applicant's amendment filed 9/14/05 has been entered.

## Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(e) the invention was described in (1) an application for patent, published under section 122(b), by another filed in the United States before the invention by the applicant for patent or (2) a patent granted on an application for patent by another filed in the United States before the invention by the applicant for patent, except that an international application filed under the treaty defined in section 351(a) shall have the effects for purposes of this subsection of an application filed in the United States only if the international application designated the United States and was published under Article 21(2) of such treaty in the English language.

Claim 11 is rejected under 35 U.S.C. 102(e) as being anticipated by Olgado et al (6,770,565 B2).

2. Regarding claim 11, Olgado et al discloses a method for improving uniformity of thickness of a thin film, adapted for a chemical vapor deposition process, comprising: forming the thin film with uniform thickness (Figure 8, reference 804) by rotating a wafer with an angle (Figure 8, reference 806) while depositing the thin film on the wafer (column 10, lines 40-67 thru column 11, lines 1-16.

# Allowable Subject Matter

- 3. Claims 12-15 are objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims.
  - 4. Claims 1-10 are allowed over the prior art of record.

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### Reasons for Allowance

5. The following is an examiner's statement of reasons for allowance: The primary reason for allowance of the claims is that the prior art neither teaches nor fairly suggest a high density plasma chemical vapor deposition process comprising a deposition system that is adapted to deposit the thin film comprises n gas output holes, wherein the first and the second deposition steps require a time interval, and at one half of the time interval, the wafer is rotated at the angle of 360/2n degrees, and n is an integer in claims 1-4 and in the context of the recited process.

The primary reason for allowance of the claims is that the prior art neither teaches nor fairly suggest a high density plasma chemical vapor deposition process comprising a deposition system that is adapted to deposit the thin film comprises n gas output holes, and performing the first and the second deposition steps require a time interval, wherein at 1/m of the time interval, the wafer is rotated at the angle of 360/(m\*n) degrees, and m and n are integers in claims 5-10 and in the context of the recited process.

### Response to Arguments

6. Applicant's arguments filed 9/14/05 have been fully considered but they are not persuasive. Olgado et al discloses a metal layer formed on a rotating substrate which may still result in a uniform thin film. Applicant is relying heavily on the preamble to give weight to the claimed limitation. Olgado still reads on claim 11. Rejection stands.

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### Conclusion

THIS ACTION IS MADE FINAL. Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the mailing date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Monica D. Harrison whose telephone number is 571-272-1959. The examiner can normally be reached on M-F 7:00am-3:30pm.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Carl Whitehead Jr. can be reached on 571-272-1702. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

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Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Monica D. Harrison AU 2813

Mdh February 24, 2006 SUPERVISORY PATENT EXAMINER

**TECHNOLOGY CENTER 2800**